CLAD TARGET MATERIAL FOR SPUTTERING

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Abstract of **JP 1096374 (A)**

PURPOSE:To prevent a clad target from thermally adhering to a backing plate by cladding a high-purity copper sheet containing trace amounts of specific elements with a sputtering target material. CONSTITUTION:A Cu sheet 4 having >=99.7% purity and containing 100-3,000wt. ppm, in total, of at least one or more elements among Zn, In, Mn, Sb, Be, Ca, Cr, Te, Y, Nb, Mo, Ta, and Sn is joined to a sputtering target material 1 by a metal bonding agent 5 made of In so as to be formed into a clad target material 6. The Cu sheet 4 of this clad target material 6 is attached to a backing plate 3 consisting of a Cu sheet with high thermal conductivity by means of an annular mounting fixture 2. By this method, the diffusion of the Cu sheet 4 of the clad target 6 into the backing plate 3 composed of Cu sheet in the course of sputtering and the resulting thermal adhesion between them can be prevented, by which the separation of the clad target 6 from the backing plate 3 is facilitated and, as a result, the exchanging operation of the target 6 can be facilitated.